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(71) Applicant (for all designated States except US): **KONINKLIJKE PHILIPS ELECTRONICS N.V.** [NL/NL];
Groenewoudseweg 1, NL-5621 BA Eindhoven (NL).

(72) Inventors; and

(75) Inventors/Applicants (for US only): **WOLTERINK, Edwin, M.** [NL/NL]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL). **DOHMEN, Gerardus, M.** [NL/NL]; c/o Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL). **SANDER, Aloysius, F., M.** [NL/NL]; c/o Prof. Holstlaan

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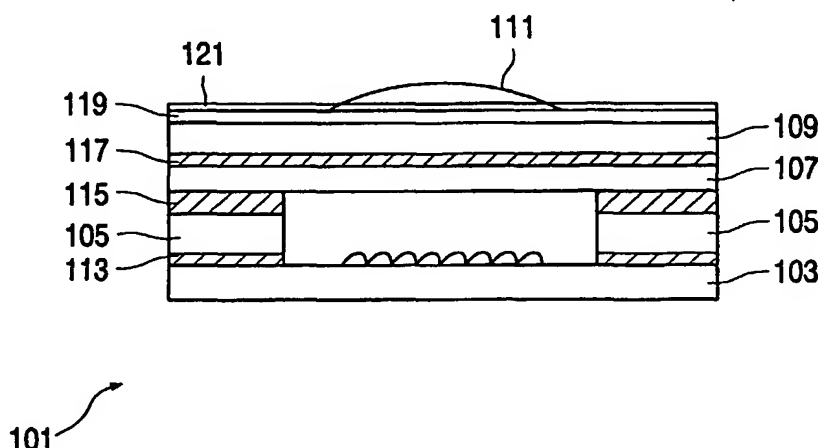
(74) Agent: **DUIJVESTIJN, Adrianus, J.**; Philips Intellectual Property & Standards, Prof. Holstlaan 6, NL-5656 AA Eindhoven (NL).

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(54) Title: CAMERA DEVICE, METHOD OF MANUFACTURING A CAMERA DEVICE, WAFER SCALE PACKAGE



(57) Abstract: The invention relates to a camera device and a method for manufacturing such a device. The camera device comprises an image capturing element, a lens element for imaging an object at the image capturing element and a spacer means for maintaining a predetermined distance along the main optical axis though the lens and the image capturing element, and lens substrate for carrying the lens wherein the spacer means comprises an adhesive layer. This enables a mass manufacturing process wherein parts of the individual camera elements can be manufactured in manifold on different substrates, after which the different substrates are stacked, aligned and joined via adhesive layers. In the manufacturing process the different distances between the plates and the wafers are adjusted and maintained via the spacer means comprising the adhesive layers. From the stack individual camera devices are sawn out.

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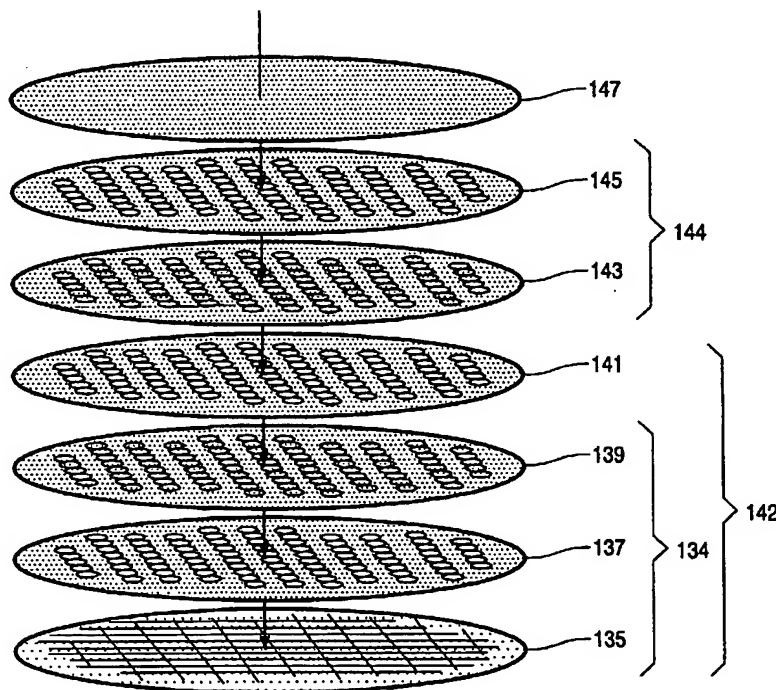
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